



## Final Product Change Notification

201308013F01

**Issue Date:** 01-Oct-2013  
**Effective Date:** 29-Dec-2013

Here's your personalized quality information concerning products Digi-Key purchased from NXP.  
For detailed information we invite you to [view this notification online](#)



### Change Category

- |  |   |   |  |
|--|---|---|--|
| <input type="checkbox"/> Wafer Fab process   | <input type="checkbox"/> Assembly Process             | <input type="checkbox"/> Product Marking                | <input type="checkbox"/> Design                    |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials           | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification  |
| <input type="checkbox"/> Wafer Fab location  | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location                  | <input type="checkbox"/> Packing/Shipping/Labeling |

## Further rollout of copper wire product types to NXP assembly site Malaysia

### Details of this Change

Scheduled changes affect product types in SOT23 package only. Further types using copper wire will be assembled in the NXP assembly plant Malaysia (APM) in addition to the NXP assembly plant Guangdong, China (APG).

The affected products were already assembled in both assembly sites before the introduction of copper wire. The introduction of copper wire for these products assembled in APG has been announced in 2010 and 2011 (see section "Related Notifications" for details).

The introduction of first copper wire products in APM has been announced in 2012 with the PCN 201204012F01.

Production will start in October 2013. The earliest production date code will be "o3" on the package and "1340" on the boxes, representing calendar week 40, 2013.

Old product: assembled in APG; wire material is copper (Cu)

Changed product: assembled in APG and APM; wire material is copper (Cu)

The design and materials of all components will remain unchanged: mold compound, die, die size, die attach, lead frame, wire material and wire diameter. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and within the same distribution).

### Why do we Implement this Change

Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper

wire shows enhanced mechanical properties.

### Identification of Affected Products

Products assembled with copper wire from APM will have a vendor code "t" and a date code marking "o3" on the package and "1340" on the boxes, representing calendar week 40, 2013 or newer.

### Product Availability

#### Sample Information

Samples are available upon request  
Latest sample request date is October 26, 2013.

#### Production

Planned first shipment 24-Dec-2013

### Impact

no impact to the product's functionality anticipated.

### Disposition of Old Products

Existing inventory will be shipped until depleted

### Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201005007F	27-Aug-2010		Change of bond wire material from gold to copper in SOT23 package
201011012F	13-Dec-2010		Change of bond wire material from gold to copper in SOT23 package and 8 inch wafer diameter
201204012F01	12-May-2012	10-Aug-2012	Change of bond wire material from gold to copper in SOT23 package

### Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 31-Oct-2013.

### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support  
**e-mail address** [DiscrQA.Helpdesk.GA-Products@nxp.com](mailto:DiscrQA.Helpdesk.GA-Products@nxp.com)

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of \$4.36 billion in 2012.

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NXP Semiconductors  
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